

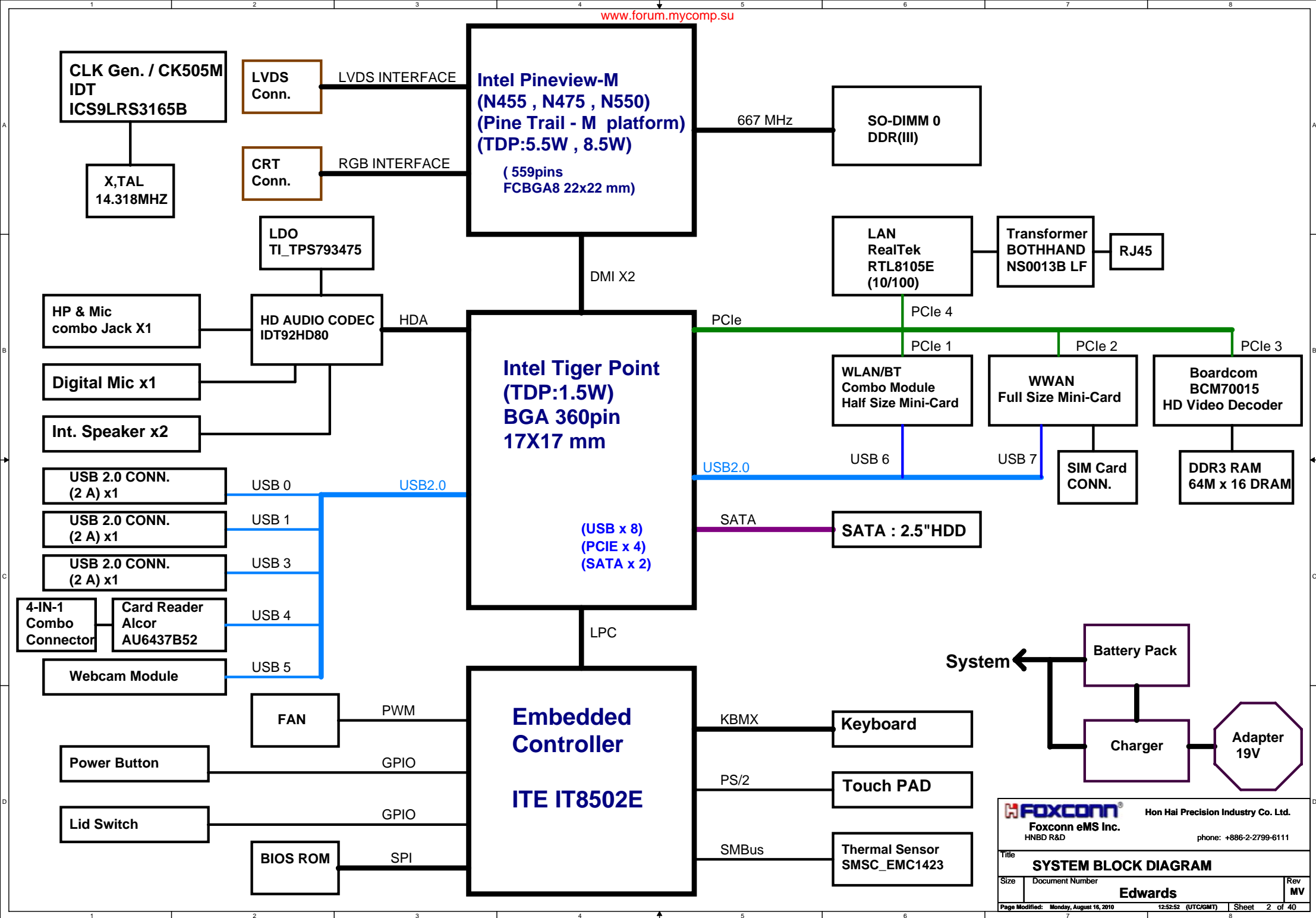
Edwards1.1 and Nano1.0 UMA MV Schematic

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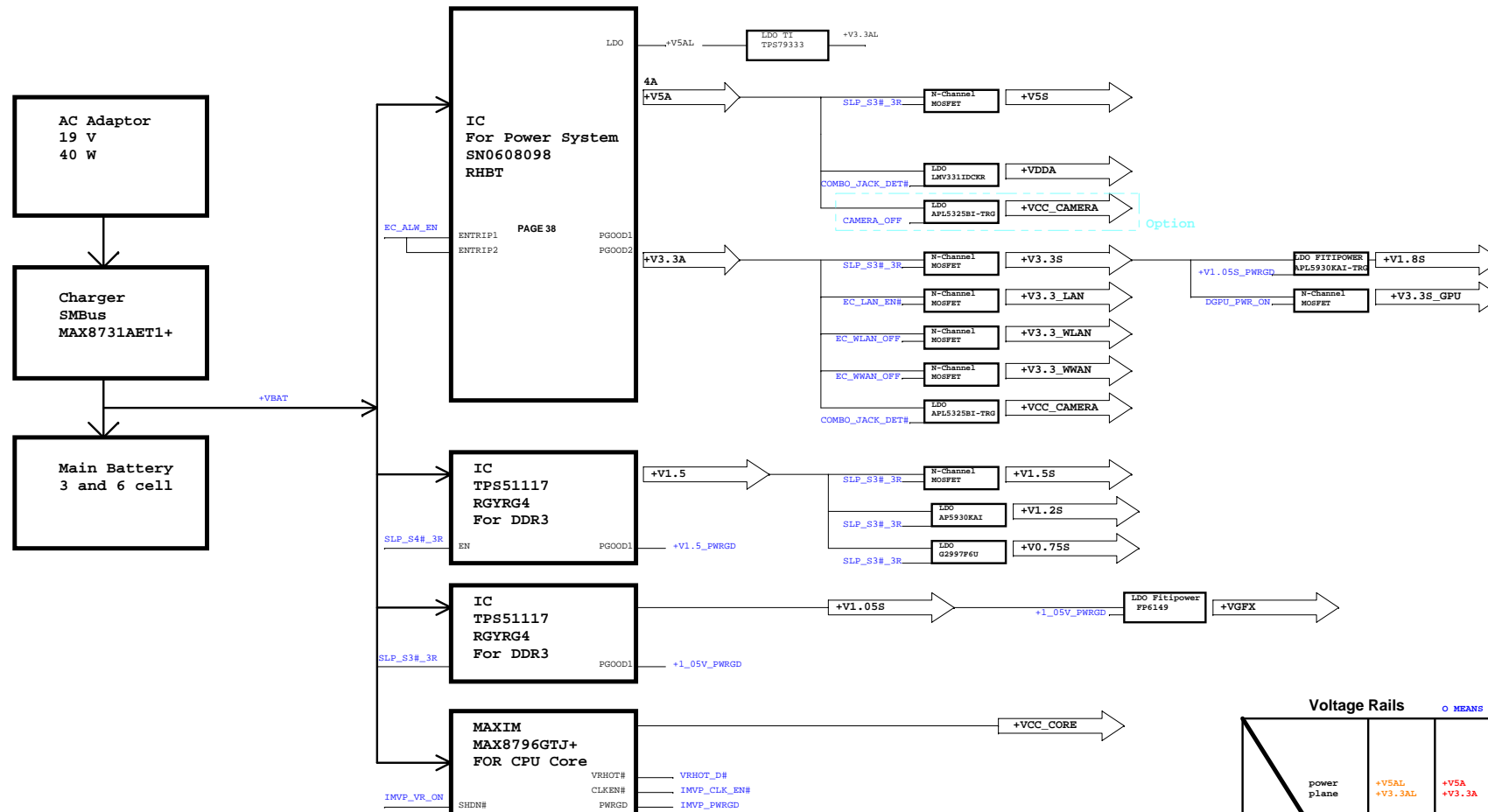
MB

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P13 : XDP DEBUG POR	P35 : DDR3 / +V1.5 & +0.75V
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P19 : TIGERPOINT(GND)5/5	
P20 : LVDS & Webcam	
P21 : WLAN & WWAN	
P22 : EC+KBC (IT8502E)	
P23 : CODEC/COMBO JACK/SPEAKER	

P. Leader	Check by	Design by
Foxconn Foxconn eMS Inc. HNBD R&D		
Hon Hai Precision Industry Co. Ltd. phone: +886-2-2799-6111		
Title COVER SHEET		
Size	Document Number Edwards	Rev MV
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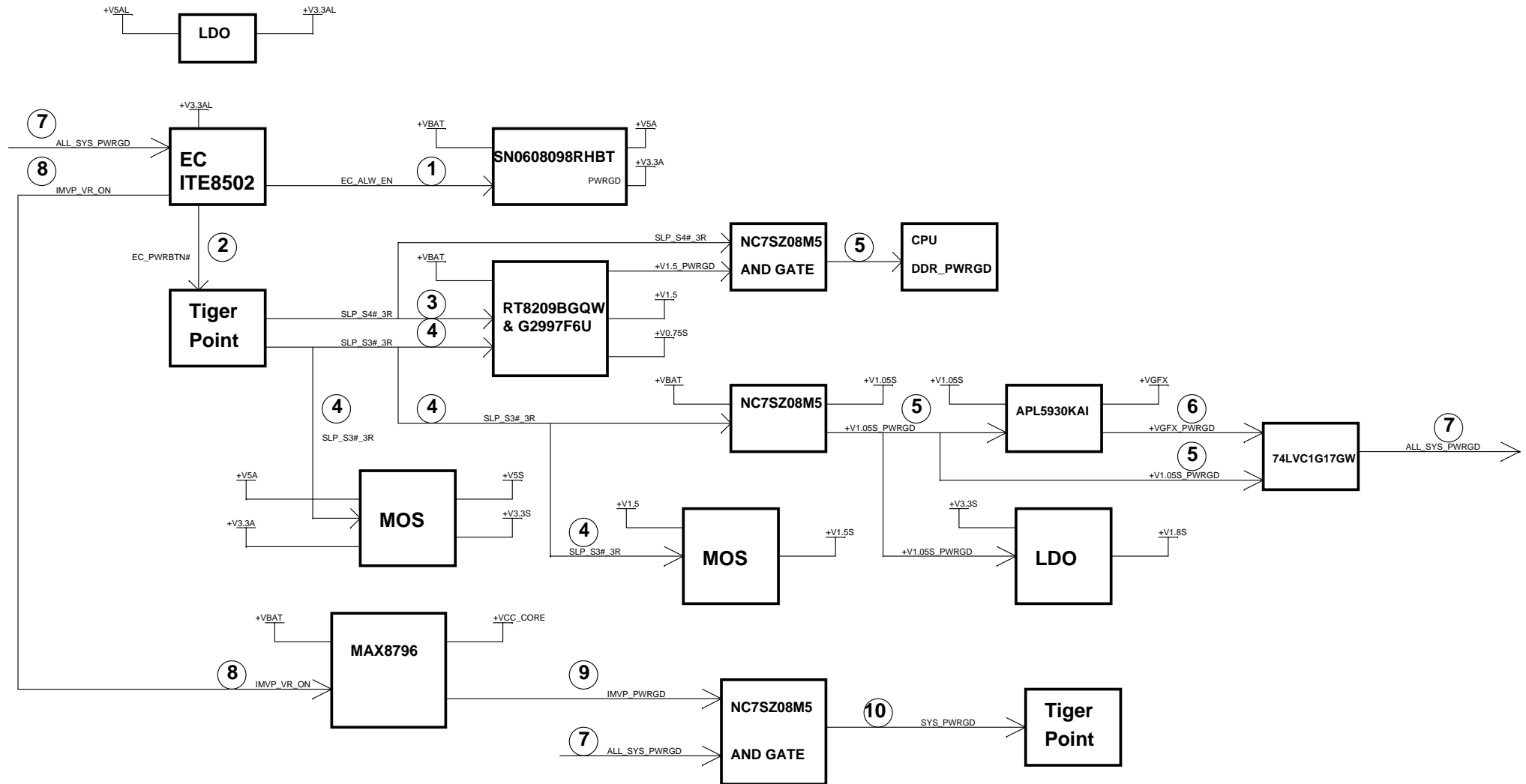
Edwards Power Block Diagram

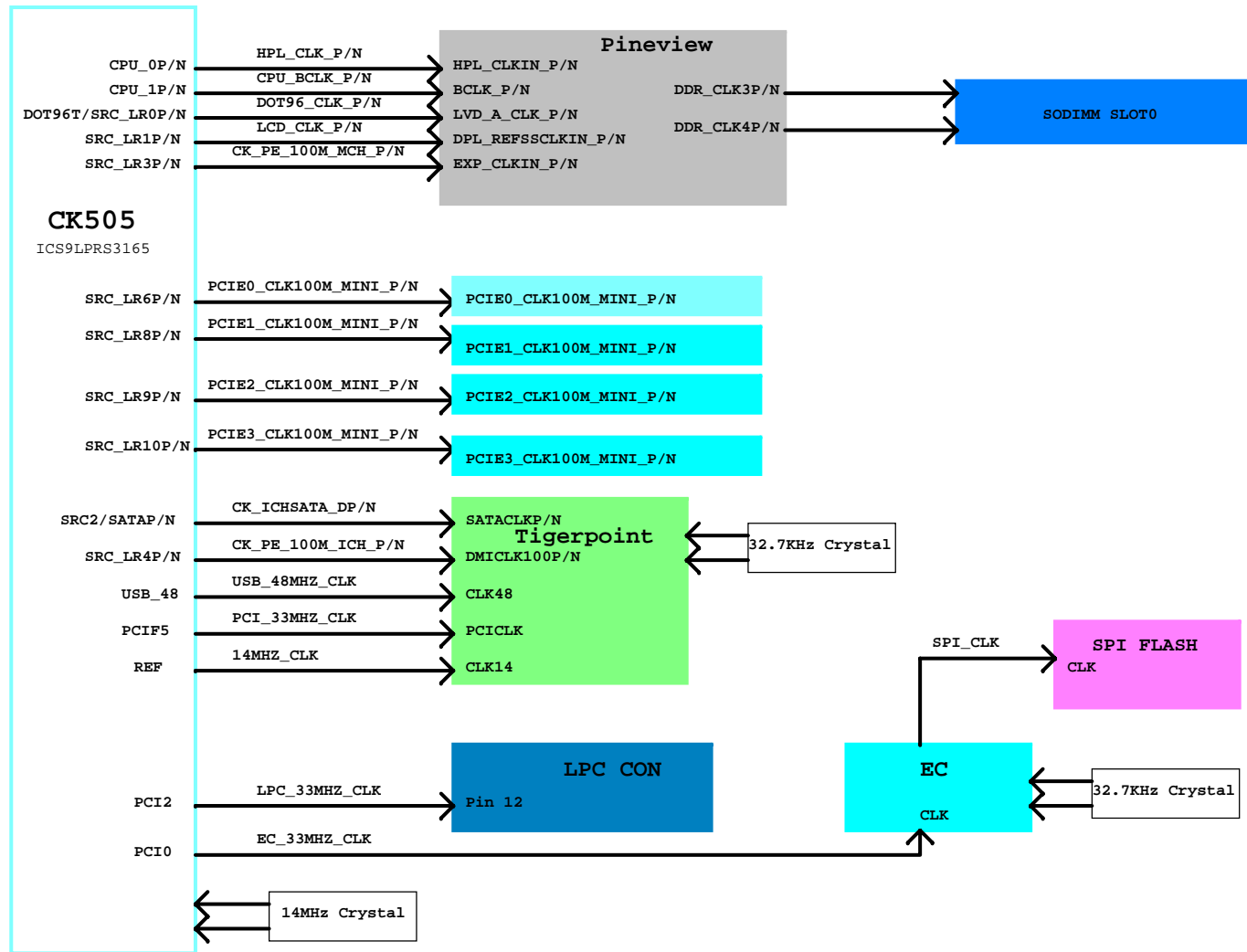


Voltage Rails 0 MEANS ON X MEANS OFF

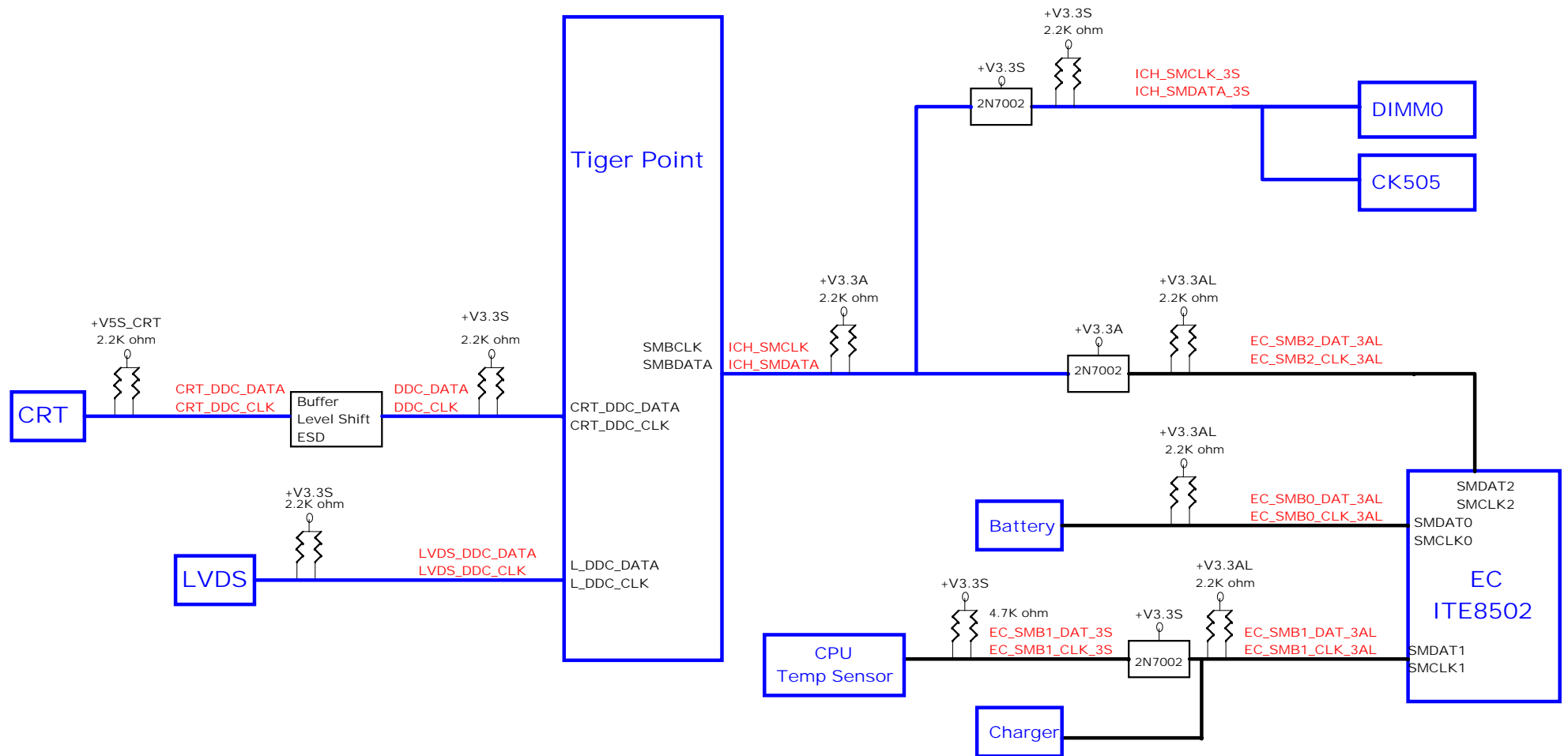
power plane \ State	+V5A +V3.3A	+V5A +V3.3A	+V1.5	+VSS +V3.3S +V1.8S +V1.5S +V1.05S +V0.75S +VCC_CORE +V1.2S +V1.5S_RD
S0	0	0	0	0
S3	0	0	0	X
S5 S4/AC	0	0	X	X
S5 S4/ Battery only	0	X	X	X
S5 S4/AC & Battery don't exist (G3)	X	X	X	X

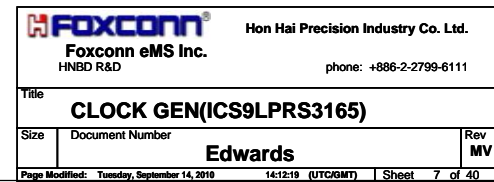
S3 : STR
S4 : STD
S5 : SOFT OFF
G3 : ME OFF



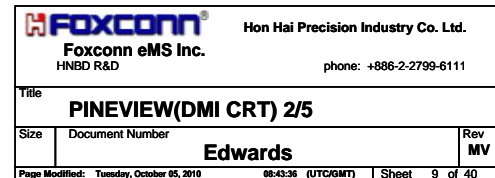


SMBUS&I2C MAP









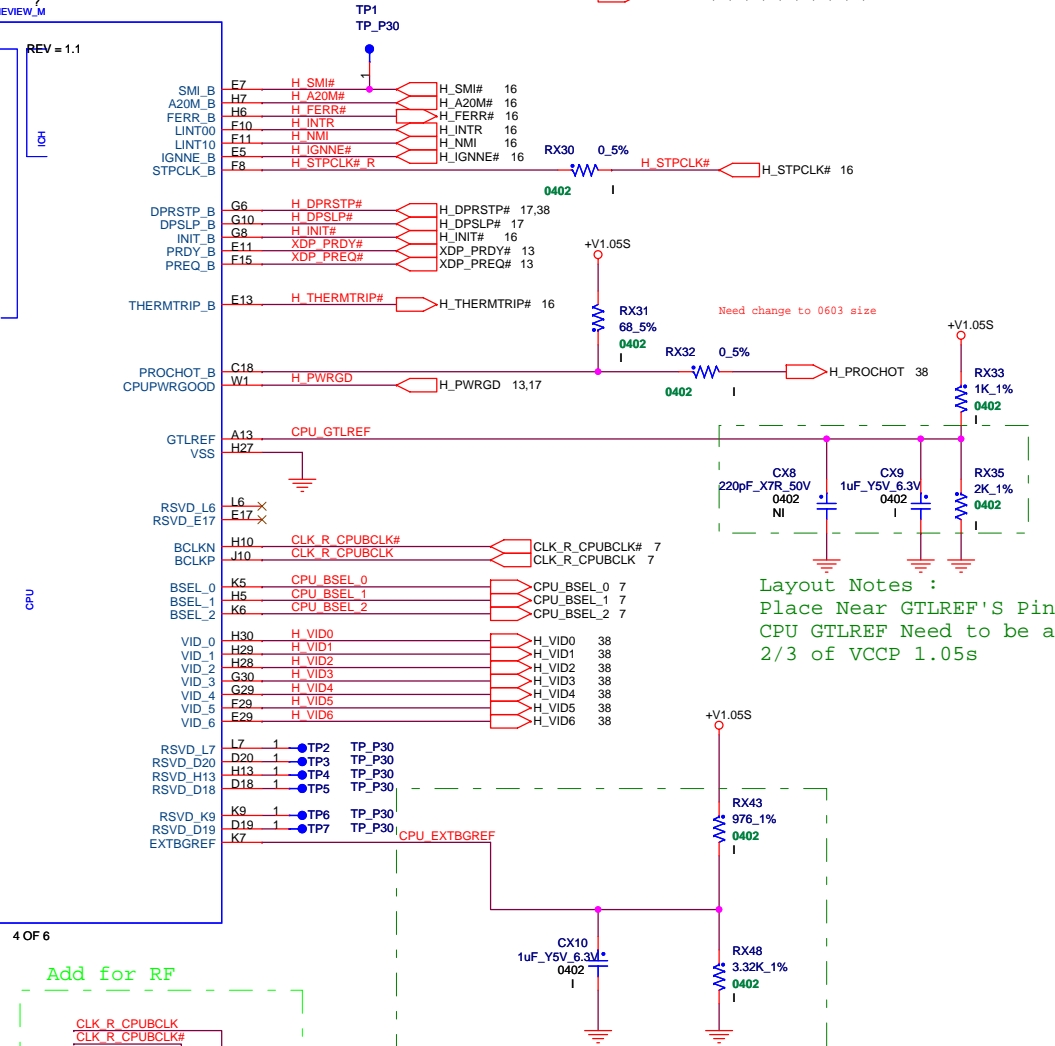


Diagram illustrating the pin connections for the RX34 to RX47 pins, showing the signal names and the 51 5% resistor values.

Pin Label	Resistor Value	Signal Name
RX34	51 5%	XDP_TDI
0402 RX36	51 5%	XDP_TMS
0402 RX37	51 5%	XDP_PREQ#
0402 RX38	51 5%	XDP_PRDY#
0402 RX39	NI	XDP_BPM#0
0402 RX40	NI	XDP_BPM#1
0402 RX41	NI	XDP_BPM#2
0402 RX42	NI	XDP_BPM#3
0402 RX44	NI	XDP_BPM_2#0
0402 RX45	NI	XDP_BPM_2#1
0402 RX46	NI	XDP_BPM_2#2
0402 RX47	NI	XDP_BPM_2#3

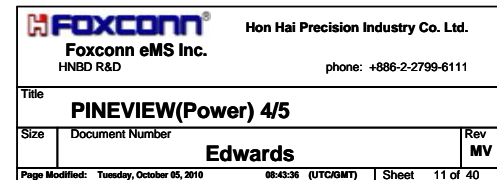
RX49 0402 2.2K 5% LVDS_DDC_CLK
 RX50 0402 2.2K 5% LVDS_DDC_DATA
 RX51 0402 2.2K 5% LCTLA_CLK
 RX52 0402 2.2K 5% LCTBL_CLK
 0402 2.2K 5% LCTBL_CLK

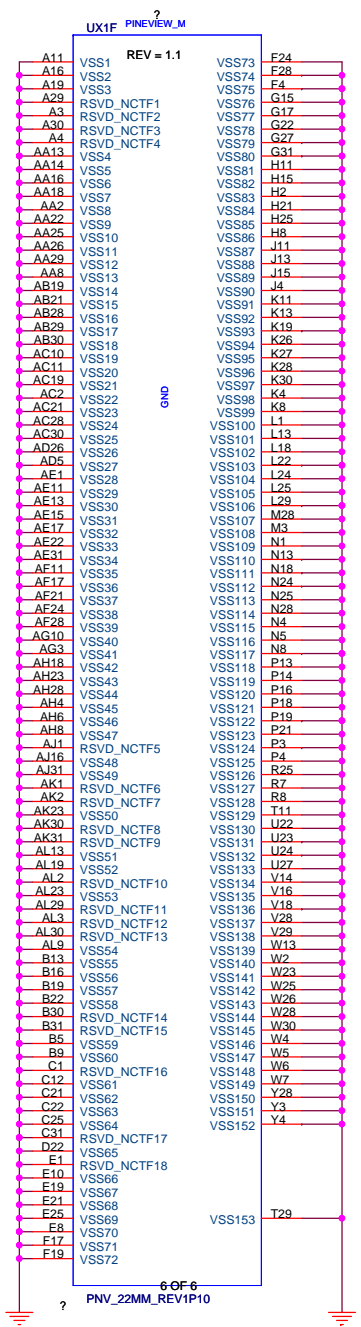
CLK R CPUBCLK
CLK R CPUBCLK#


CX53
12pF_NPO_50V
0402
NI

CX54
12pF_NPO_50V
0402
NI

Layout Notes :
EXTBGRF MAX TRACE LENGTH OF 500 MIL
AND 5 MIL SPACING within 0.5" of CPU







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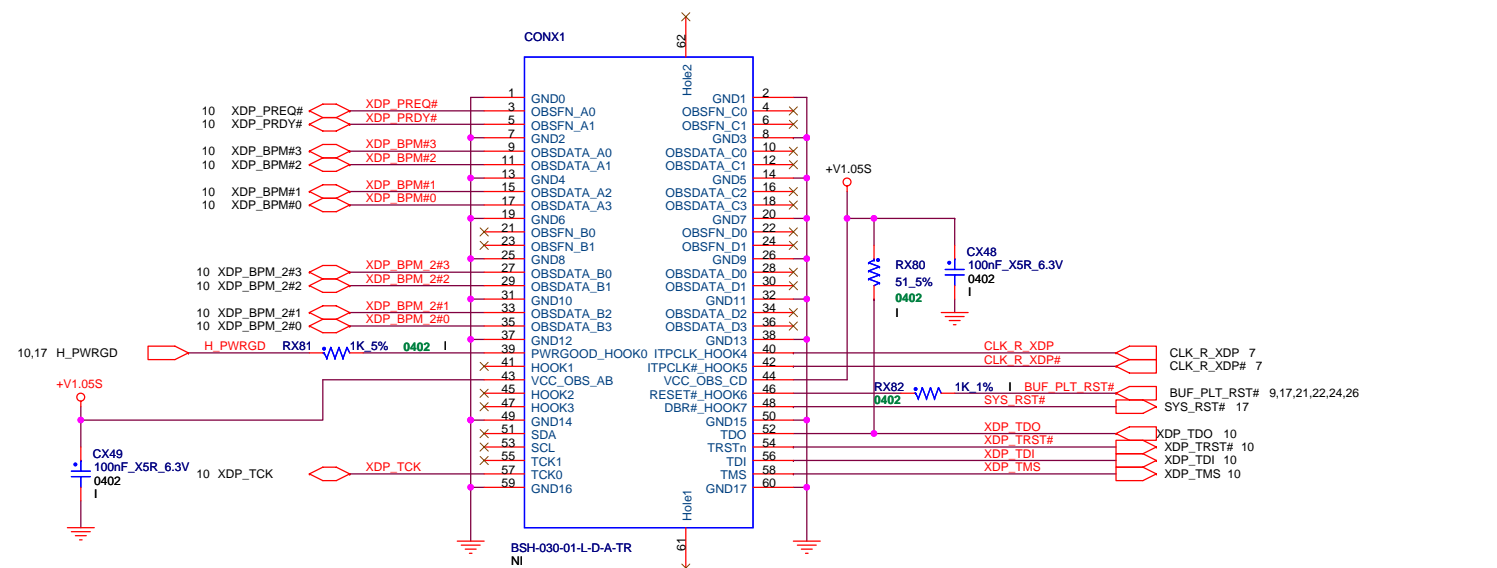
Title

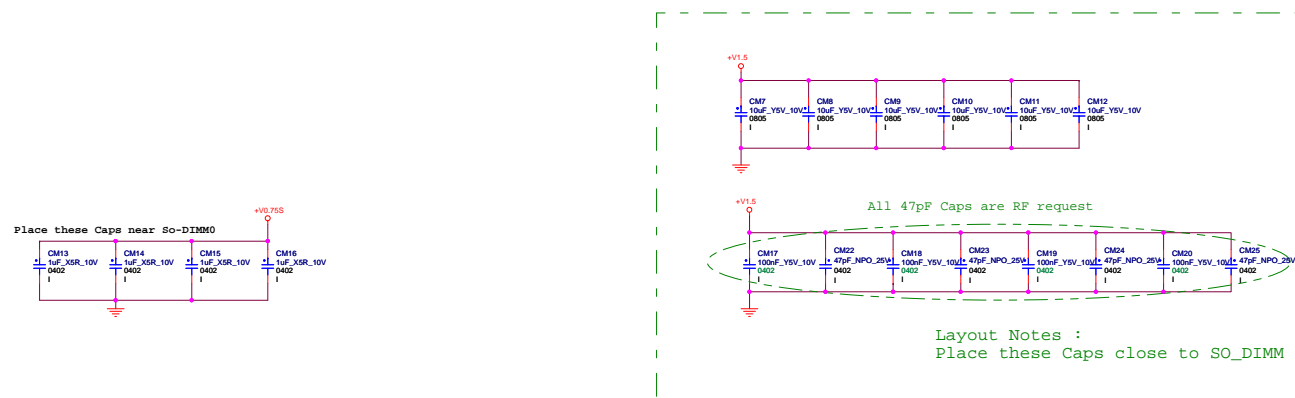
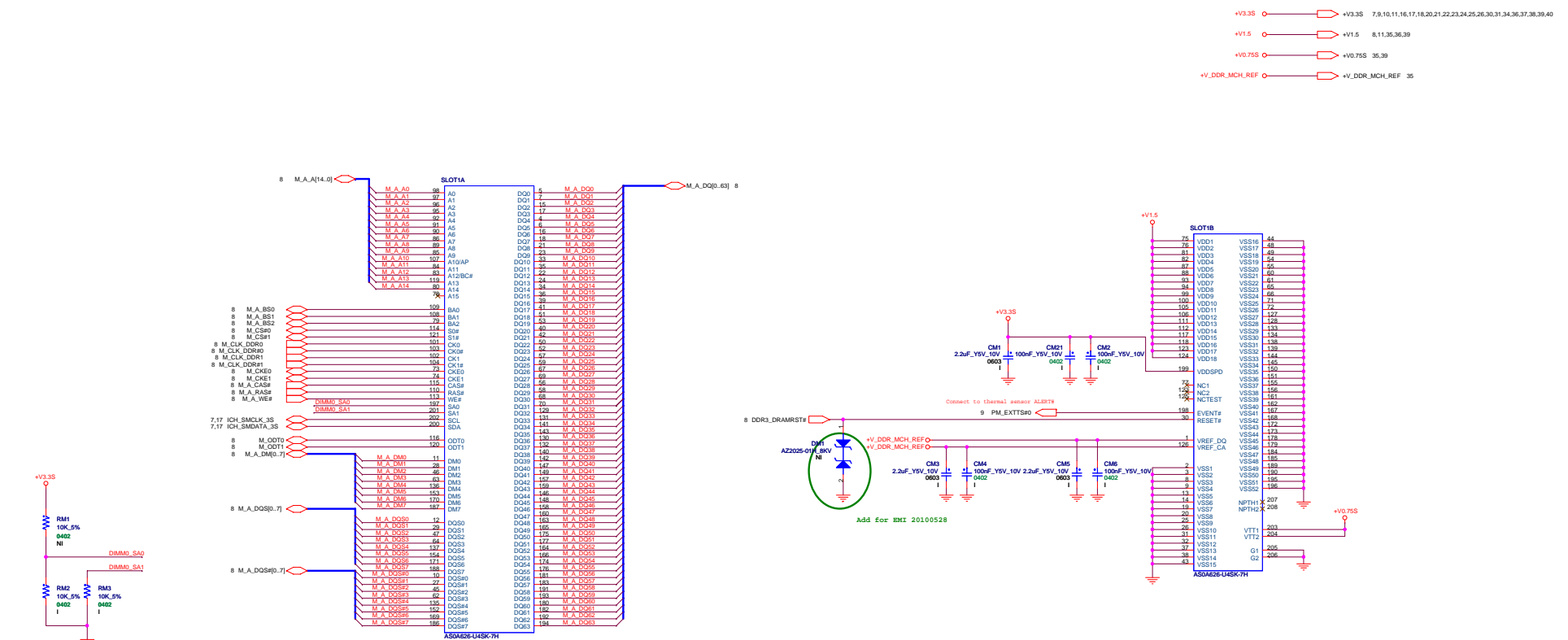
PINEVIEW(GND) 5/5


Size	Document Number	Rev
	Edwards	MV


Page Modified: Tuesday, October 05, 2010 08:43:36 (UTC/GMT)

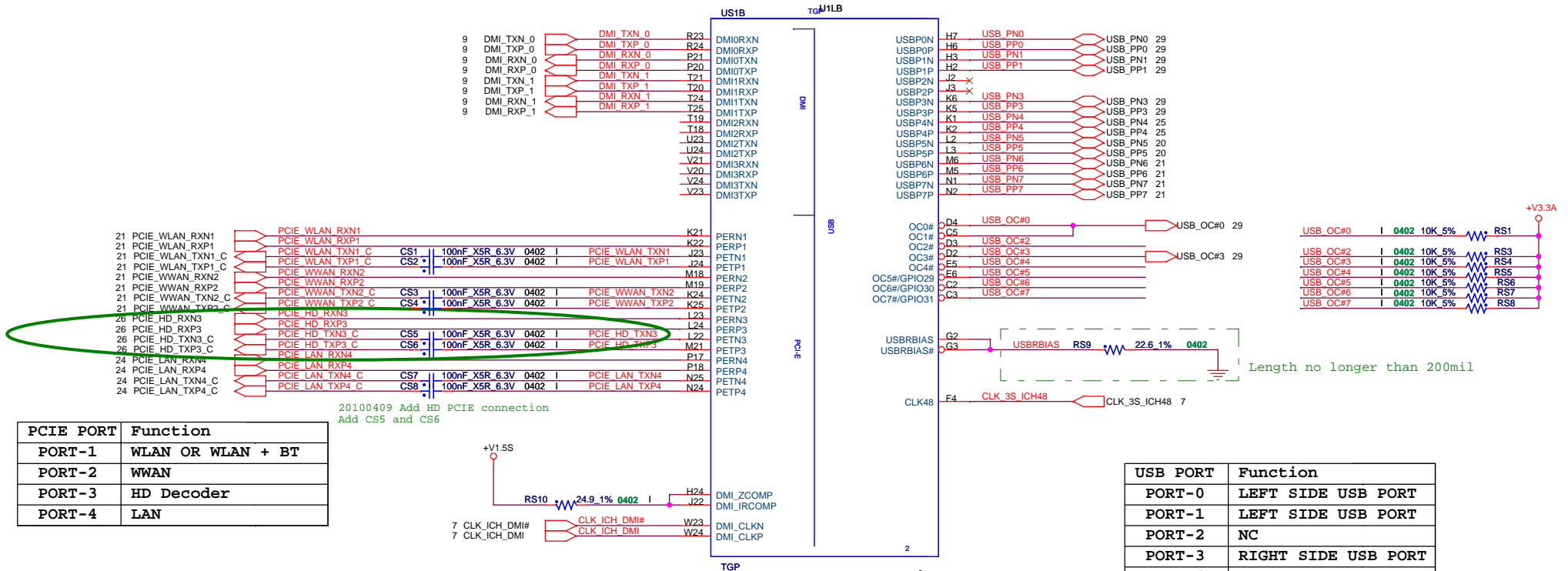
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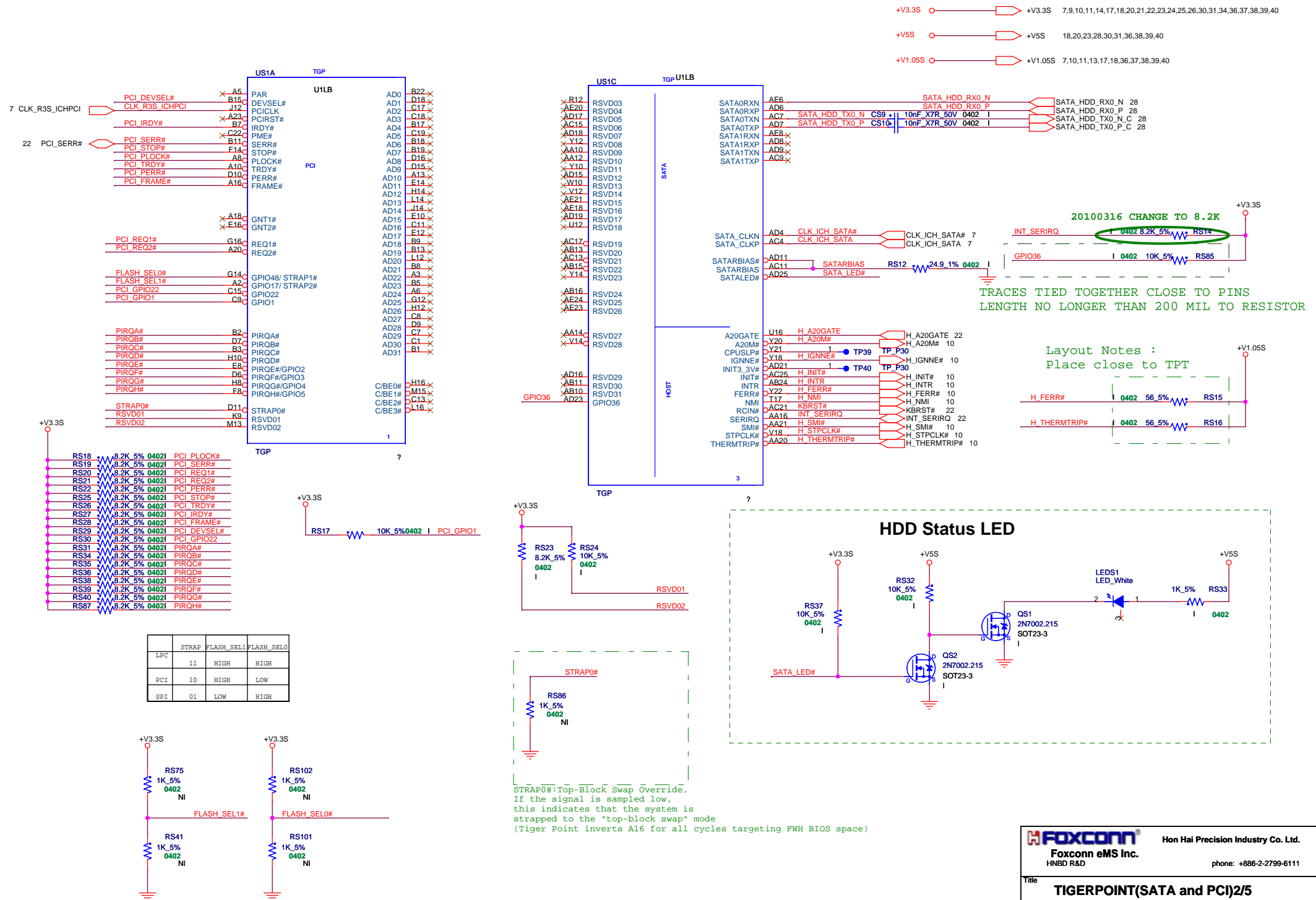
+V1.5S  +V1.5S 11,18,21,26,39

+V3.3A  +V3.3A 17,18,21,22,24,33,34,35,39,40

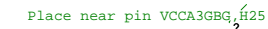


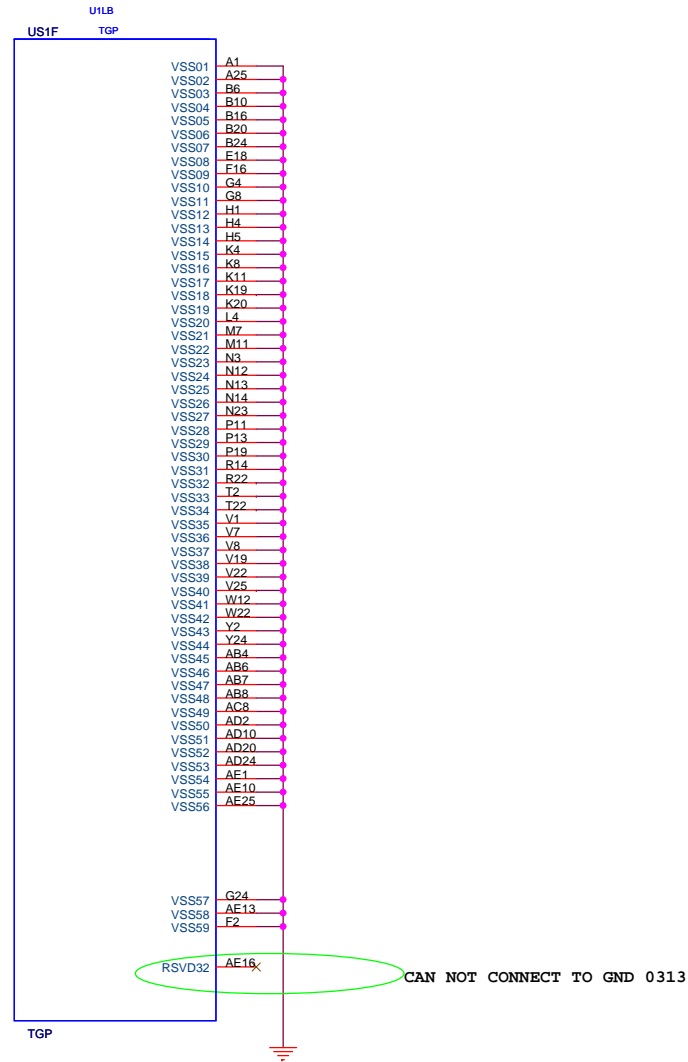
PCIE PORT	Function
PORT-1	WLAN OR WLAN + BT
PORT-2	WWAN
PORT-3	HD Decoder
PORT-4	LAN

USB PORT	Function
PORT-0	LEFT SIDE USB PORT
PORT-1	LEFT SIDE USB PORT
PORT-2	NC
PORT-3	RIGHT SIDE USB PORT
PORT-4	CARD READER
PORT-5	CAMERA
PORT-6	WLAN OR WLAN + BT
PORT-7	WWAN

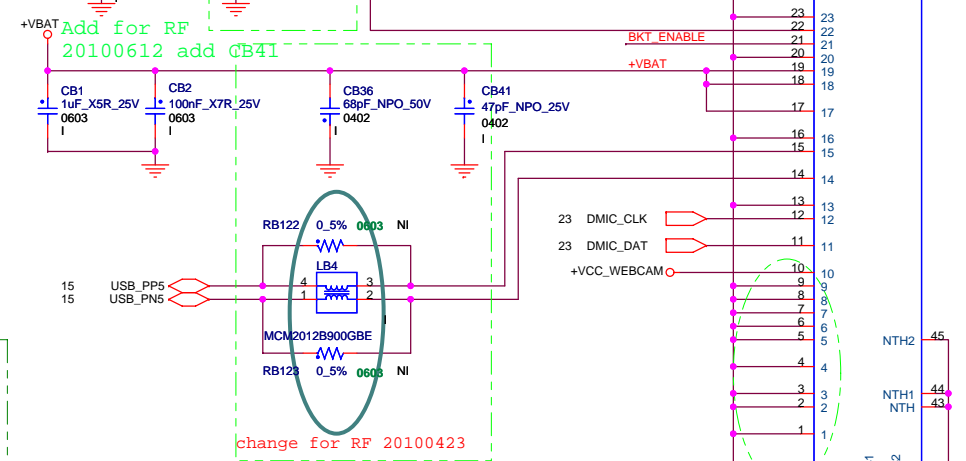
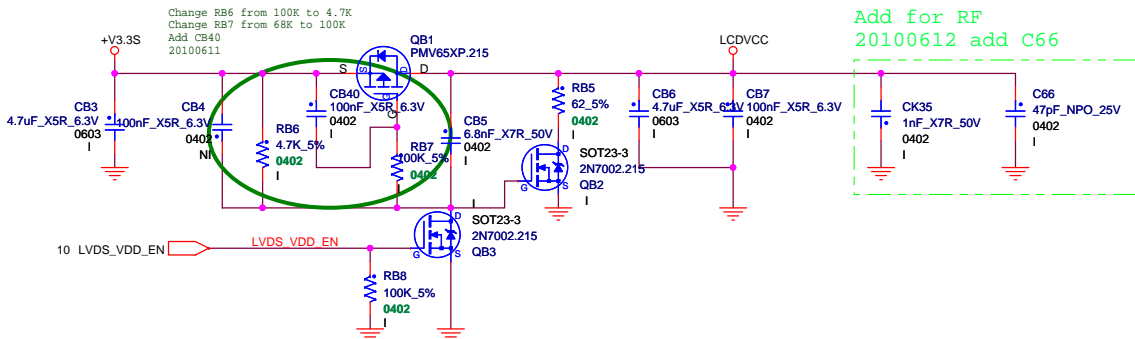
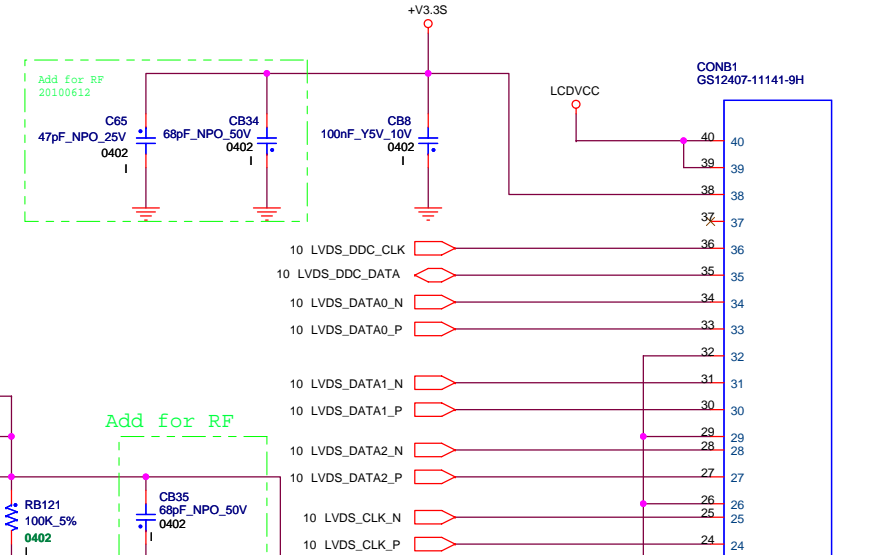
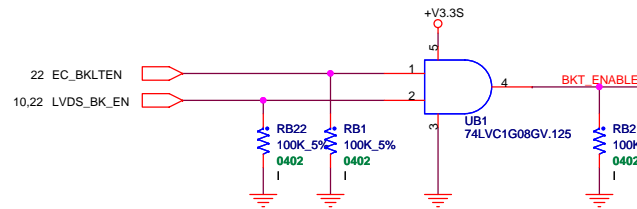




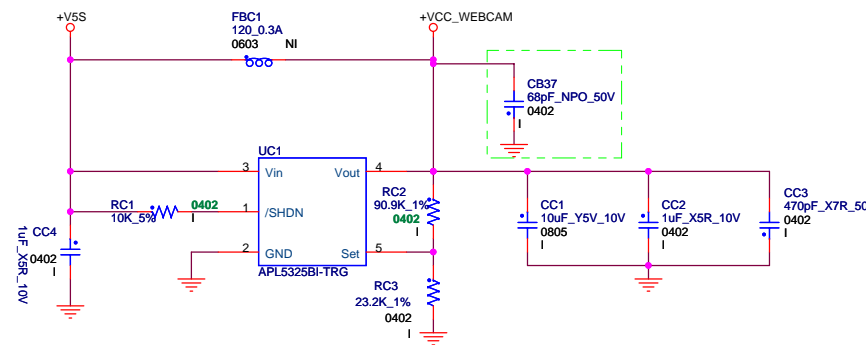




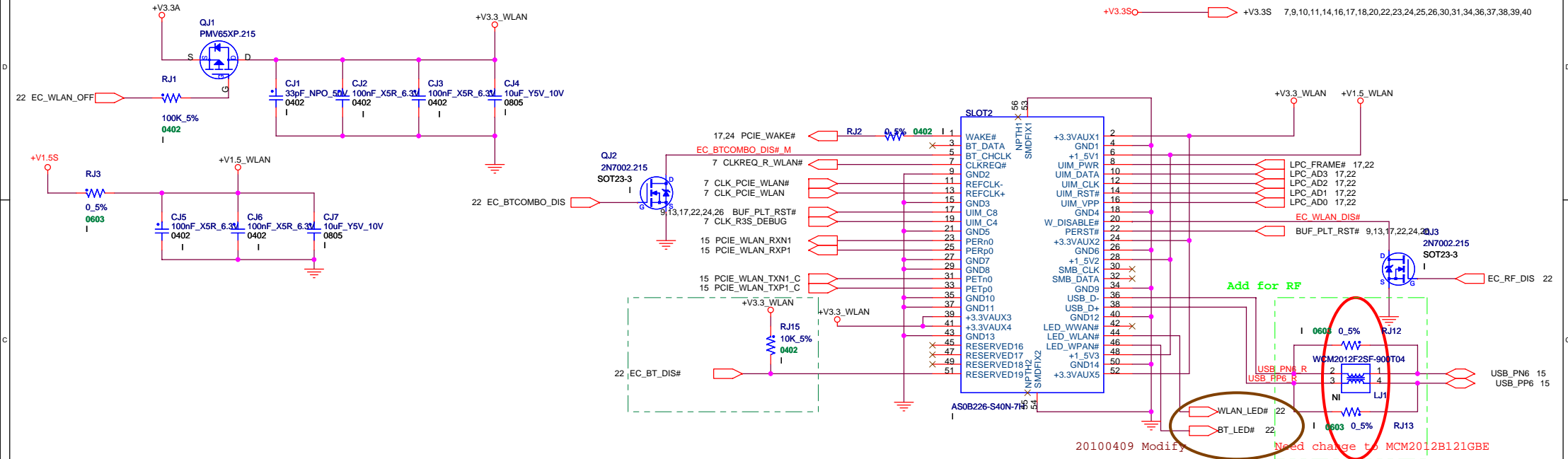
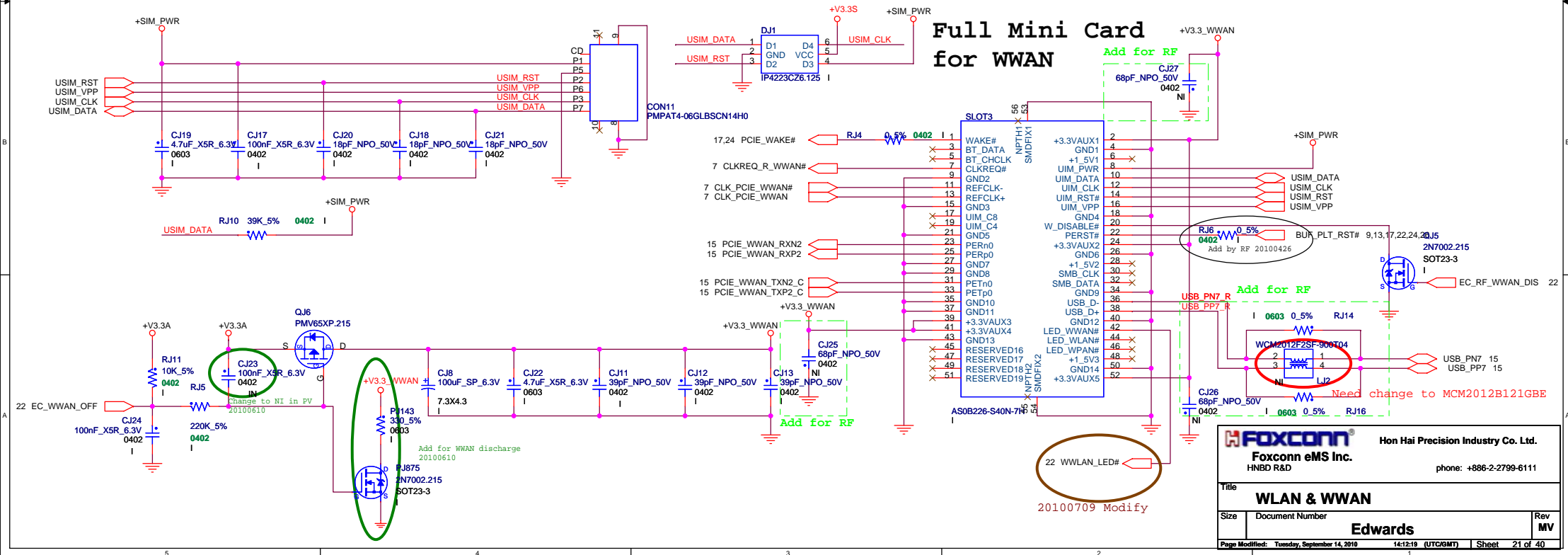
+VBAT		+VBAT	33,34,35,36,38,40
+V3.3S		+V3.3S	7,9,10,11,14,16,17,18,21,22,23,24,25,26,30,31,34,36,37,38,39,40
+V5S		+V5S	16,18,23,28,30,31,36,38,39,40

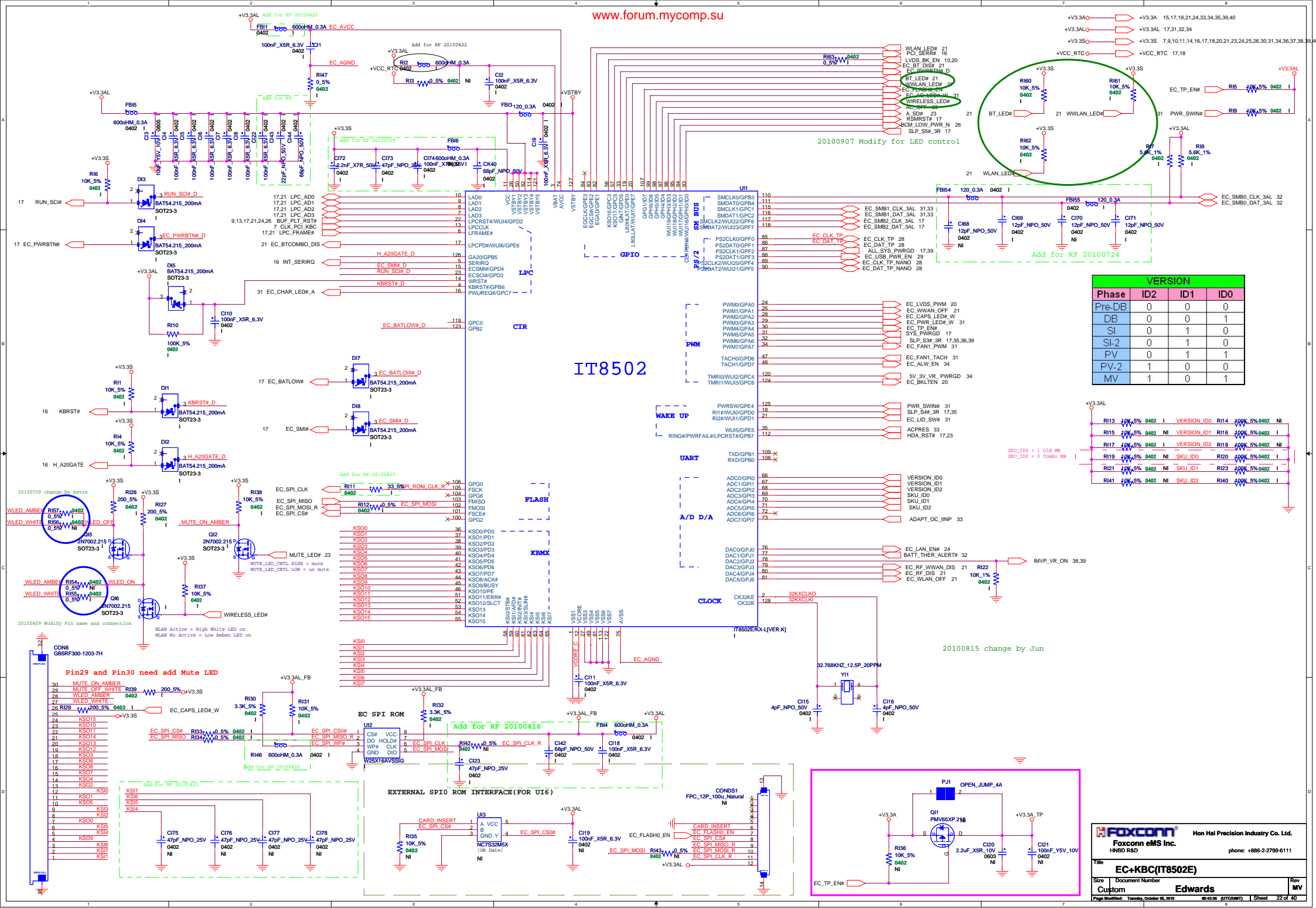


Camera Power



Half Mini Card
for WLAN

Full Mini Card
for WWAN [Add for](#)
[-----](#)



VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	

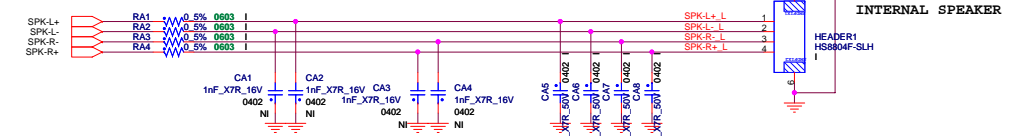
VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	

VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	

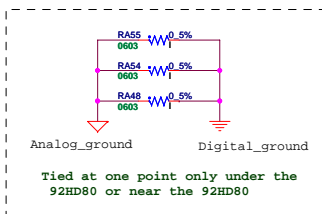
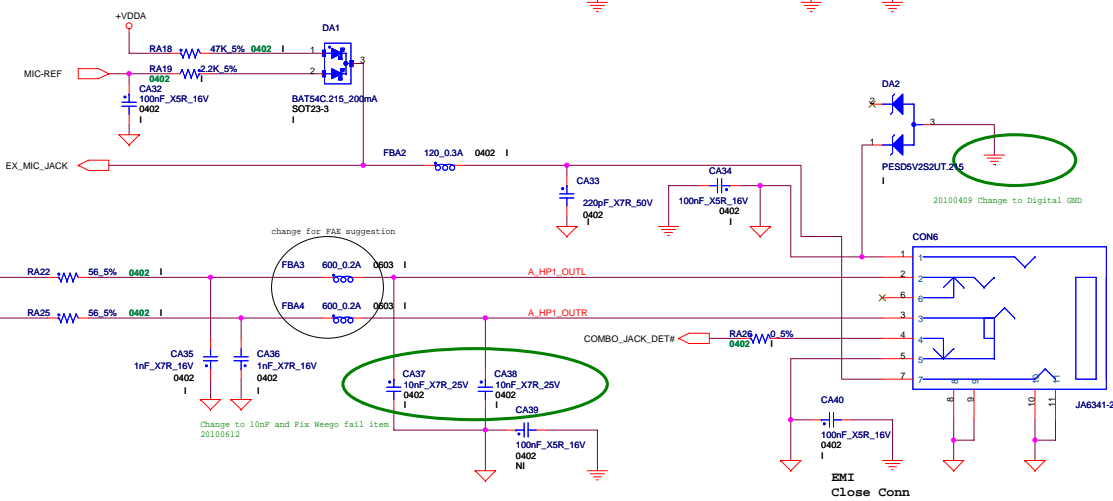
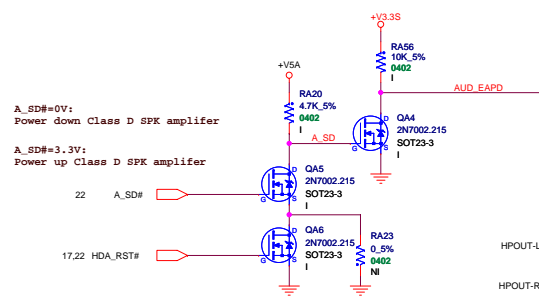
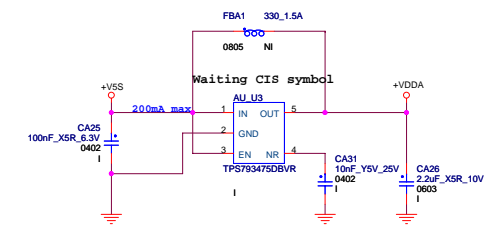
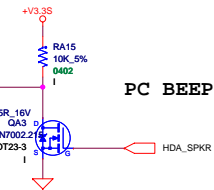
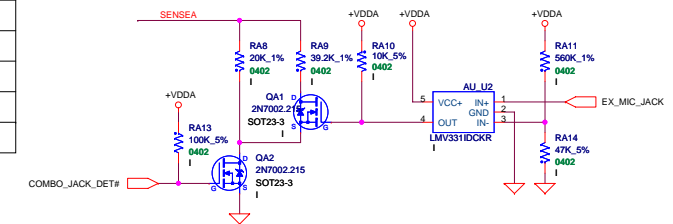
VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	

VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	

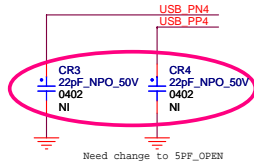
VERSION				
Phase	ID2	ID1	ID0	
Pre-DB	0	0	0	
DB	0	0	1	
SI	0	1	0	
SI-2	0	1	0	
PV	0	1	1	
PV-2	1	0	0	
MV	1	0	1	



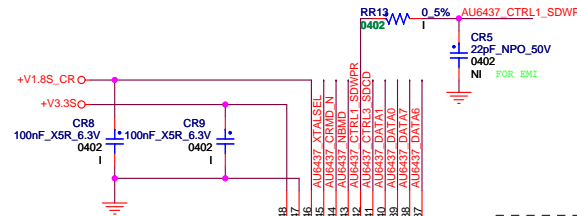
PORT	Discription	Sense
A	Microphone	SENSE_A
B	Headphone	SENSE_A
C	NO USE	
D	SPKR	
E	NO USE	
F	NO USE	



CR3,CR4 Close to CR_U1

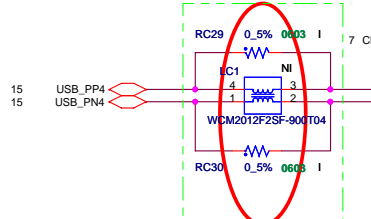


CR_C12 Close to CN3



+V3.3S 7,9,10,11,14,16,17,18,20,21,22,23,24,26,30,31,34,36,37,38,39,40

Add for RF



The capacitor CR7 must closes between VDD33P (Pin 5) and VS33P (Pin 8) without via.

The capacitor CR10 must closes between VDD (Pin 11 & Pin 12) and VS33P (Pin 8) without via. If not, it will cause worse jitter at USB signal.

The capacitor CR11 & CR12 must be close to pin15 & 17

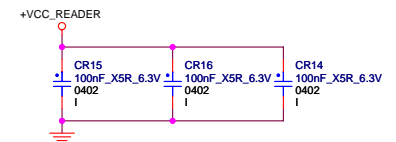
AU6437_XTALSEL RR5 0.5% 0402 NI
Clock input selection
'1' for 48MHz input [Default]
'0' for 12MHz input

AU6437_SDWPEN RR6 0.5% 0402 NI
SD write protect
1:decided by SDWP[Default]
0:letting SD always write-able

AU6437_CRMD_N RR7 0.5% 0402 NI
SD interface tri-state
'1' for tri-state
'0' for normal [Default]

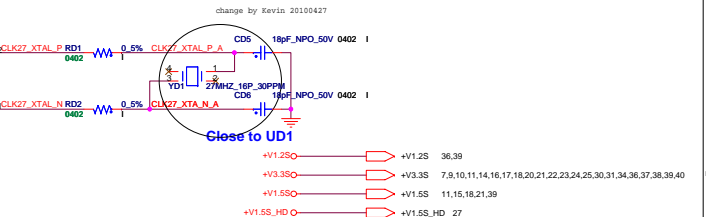
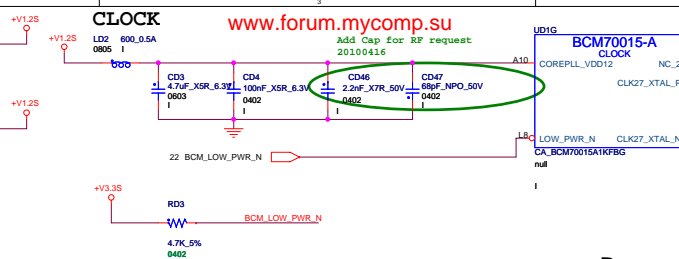
AU6437_GPI2 RR9 0.5% 0402 NI
XD CIS check
'1' for check [Default]
'0' for not check

AU6437_NBMD RR10 0.5% 0402 NI
Power saving mode
'1' for enable [Default]
'0' for disable



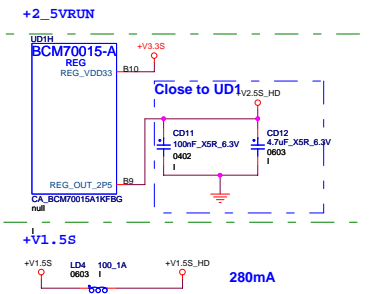
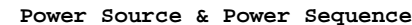
FOXCONN Foxconn eMS Inc. HNBD R&D		Hon Hai Precision Industry Co. Ltd. phone: +886-2-2799-6111	
Title Card Reader			
Size	Document Number	Rev	MV
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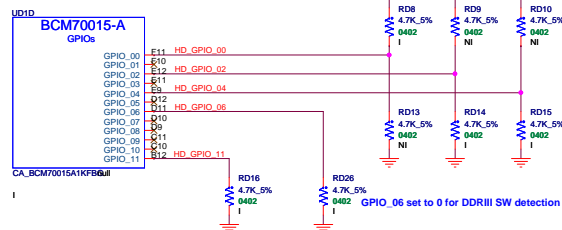
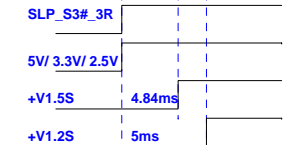


When the LOW_PWR_N signal is driven low, the BCM70015 enters an extremely low-power state (shut off internal logic & clock are inactive)

The DDR_BA2 (L1) should be reserved for 1G DDR2 (8 banks) purpose.
W9751G6IB was 512M DDR2 (4 banks).



Broadcom recommends 3.3V -> 1.5V -> 1.2V
bring up time no longer then 5ms for each
power plane.

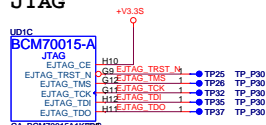


UD1F

BCM70015-A
EEPROM
EEPROM_CLK
EEPROM_DATA

D8
B8

CA_BCM70015A1KF8G



UD1E

BCM70015-A

BSC

BSC_S_SCL

BSC_S_SDA

M9

M8

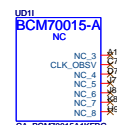
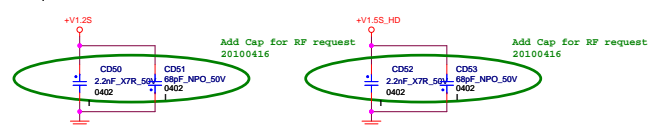
TP36

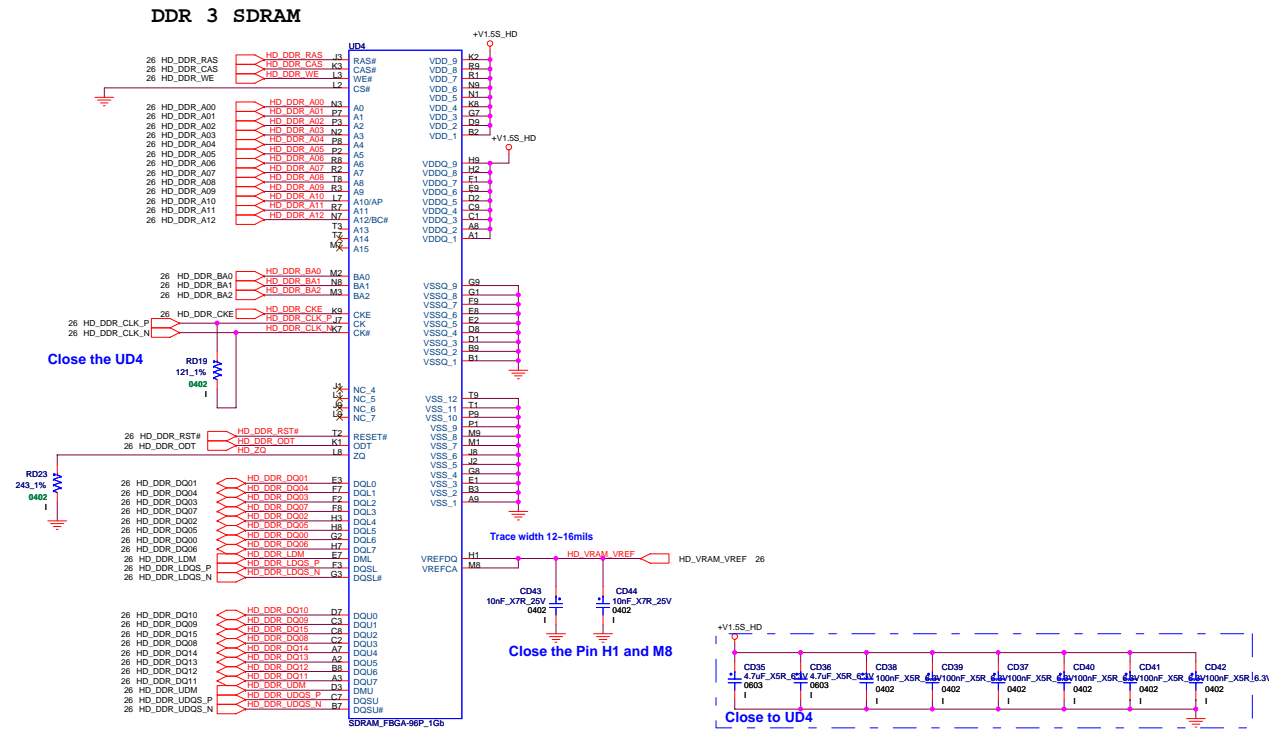
TP38

TP30

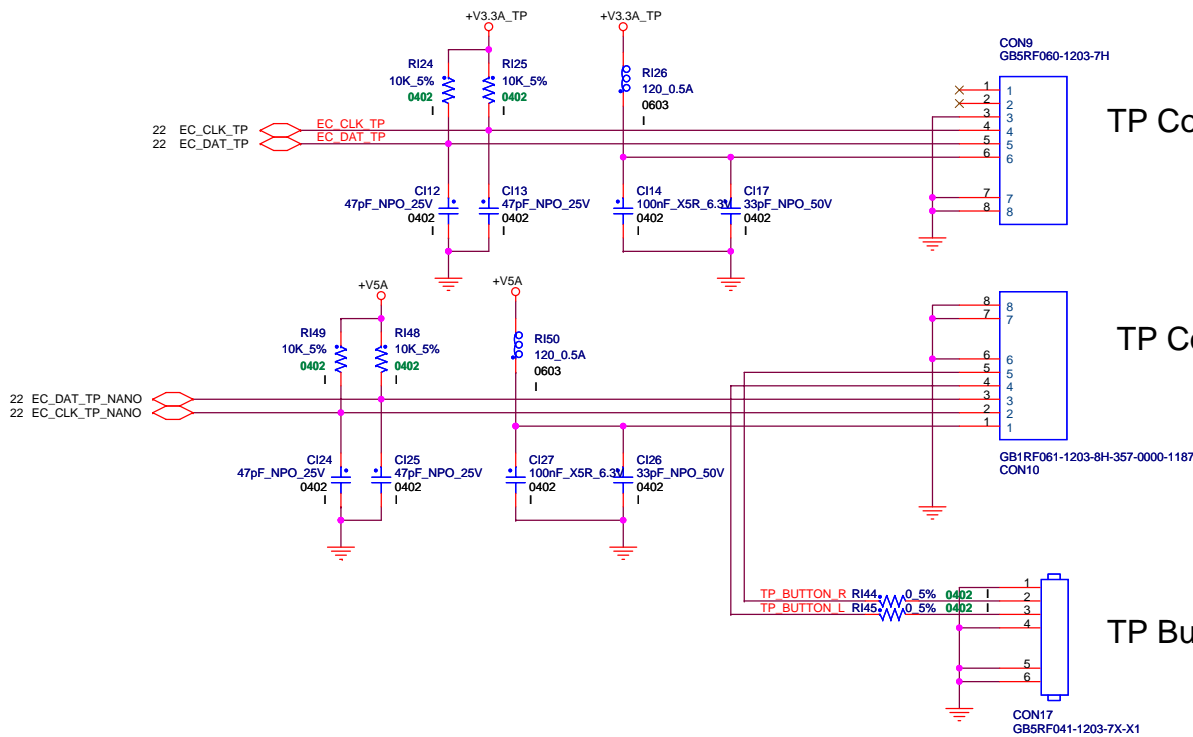
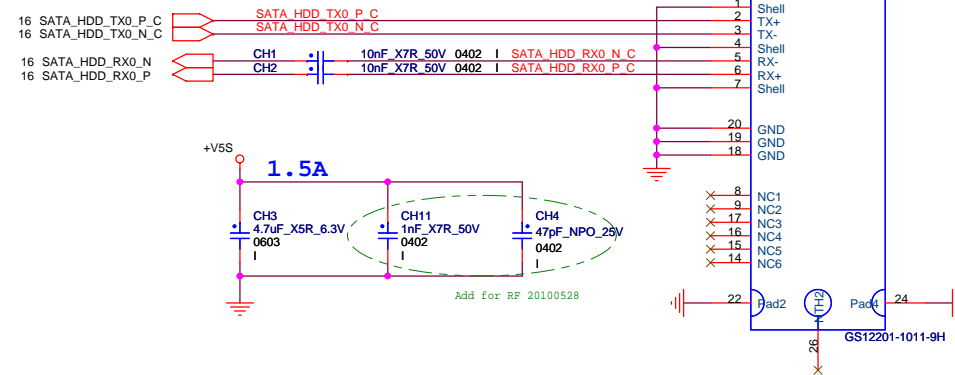
TP32

CA_BCM70015A1KFBG

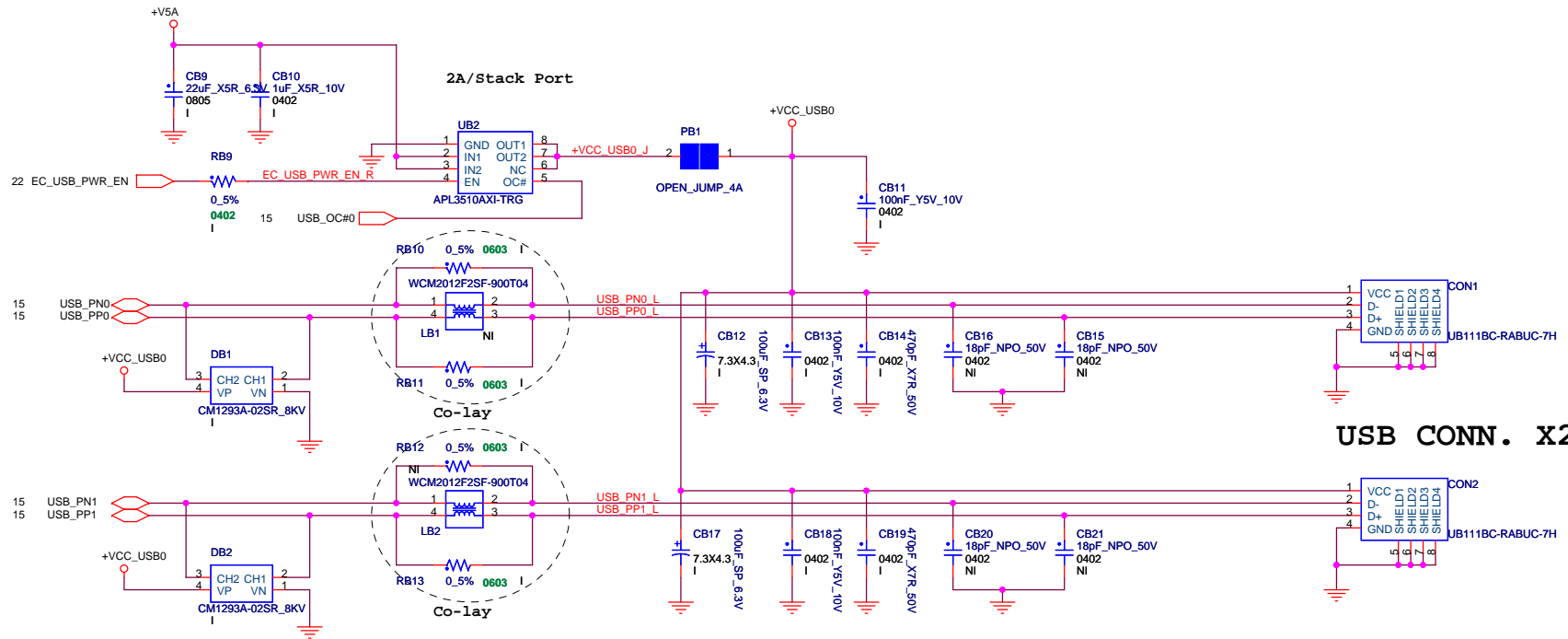
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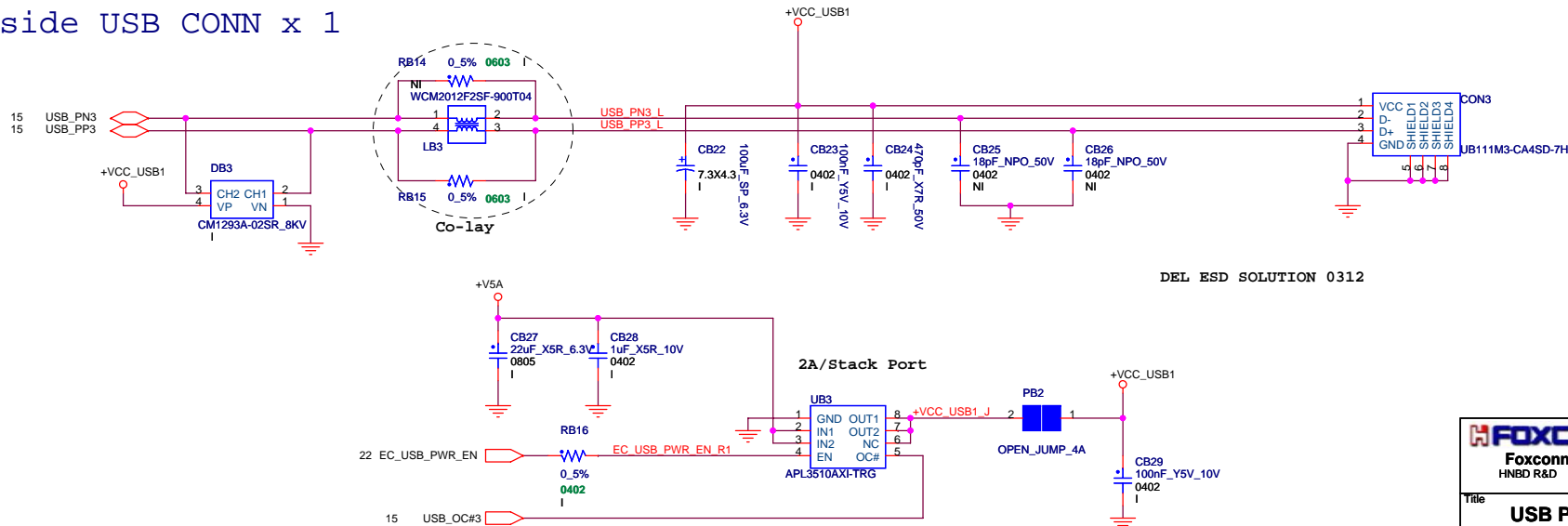
SATA HDD CONN



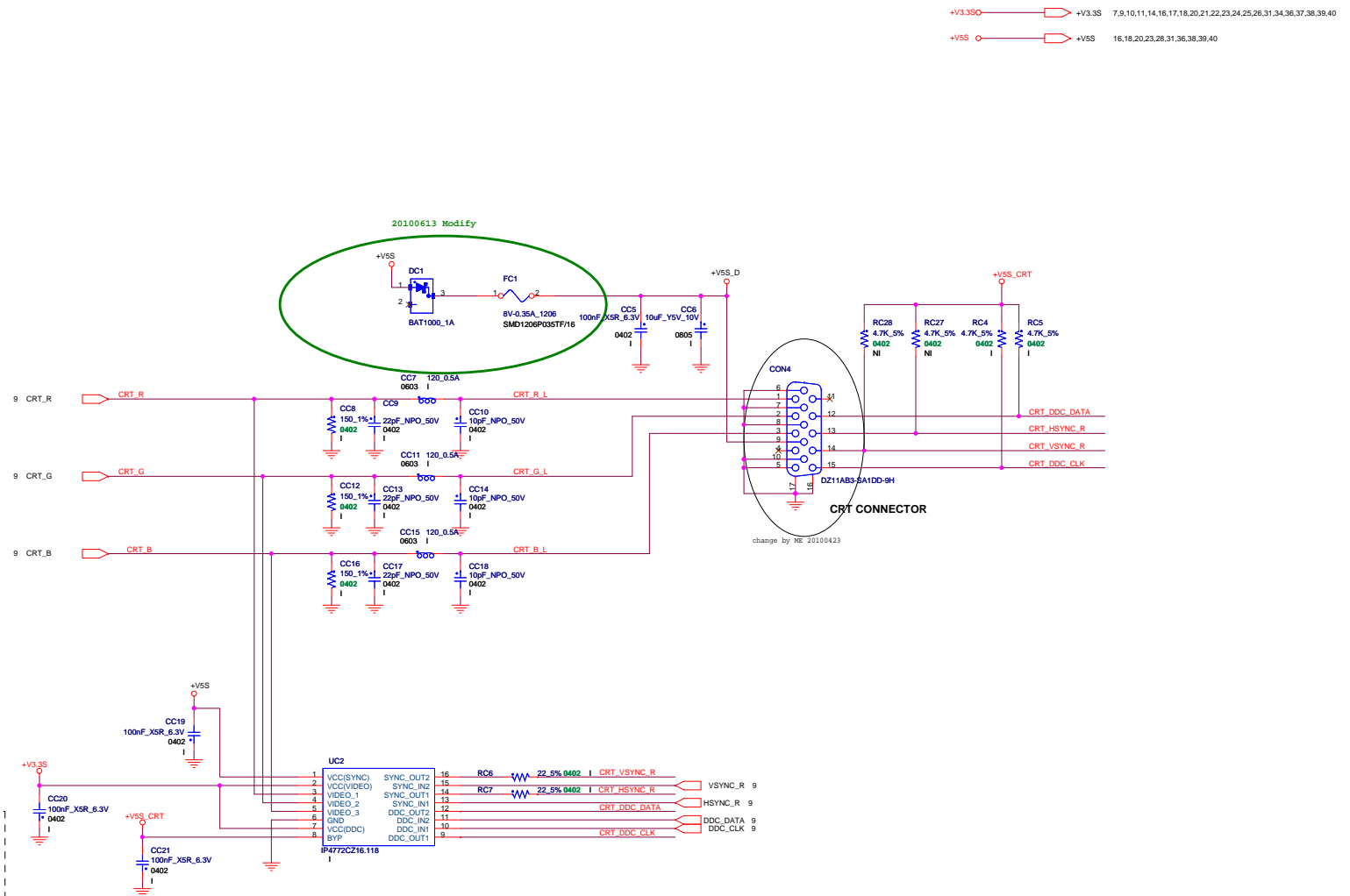
Right side USB CONN x2



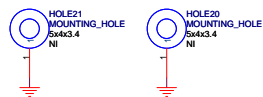
Left side USB CONN x 1



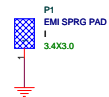
DEL ESD SOLUTION 0312



CPU Hole



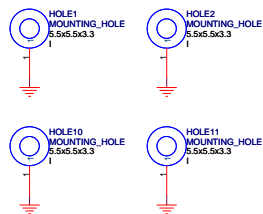
EMI SPRING



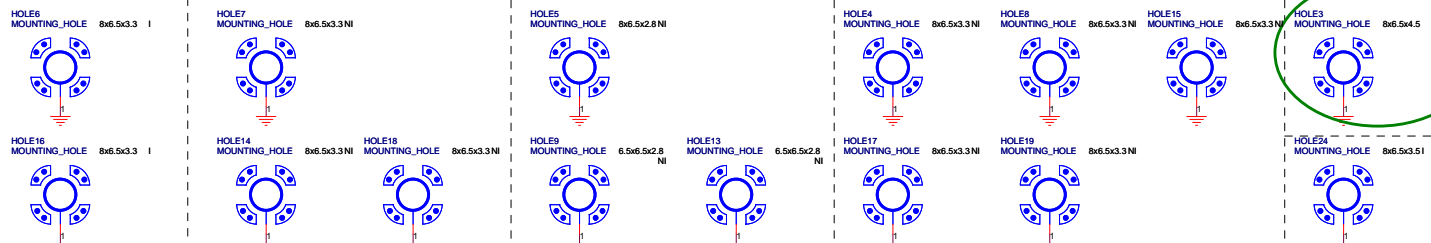
add for RF 20100423

Top x Bottom x Hole(mm) change screw pad by Kevin 20100421

Mini Card Hole



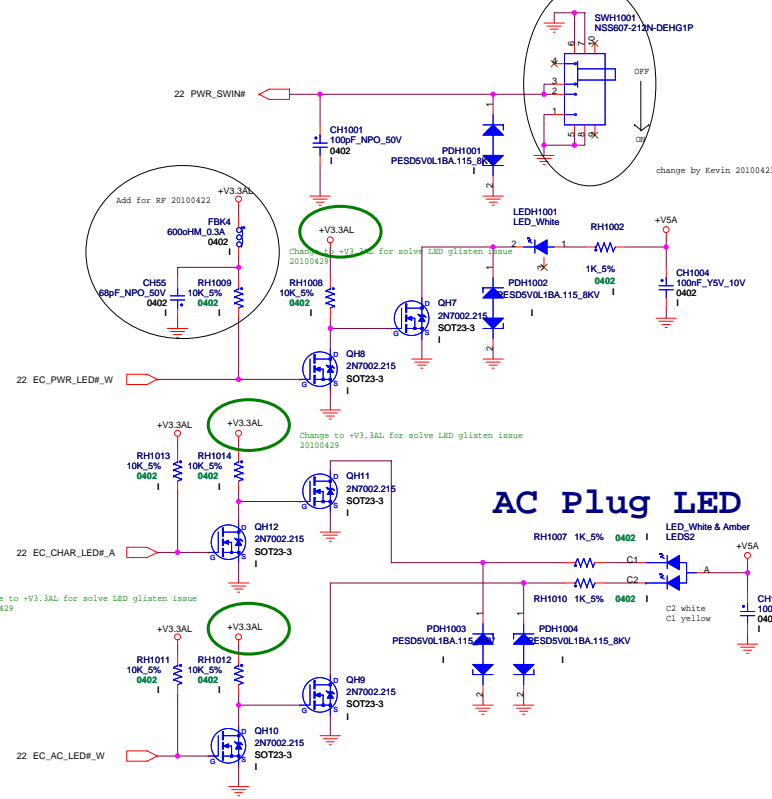
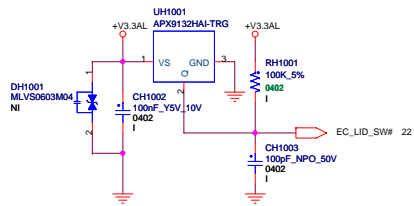
FAN Hole



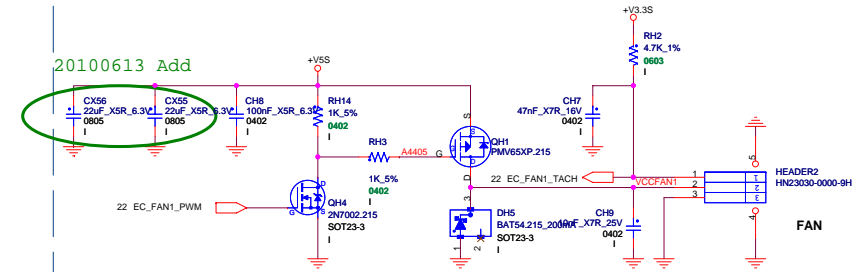
20100530 change for HE

Power Switch and Power LED

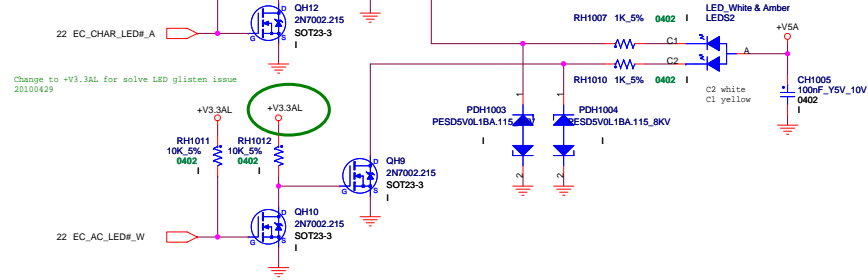
LID Switch



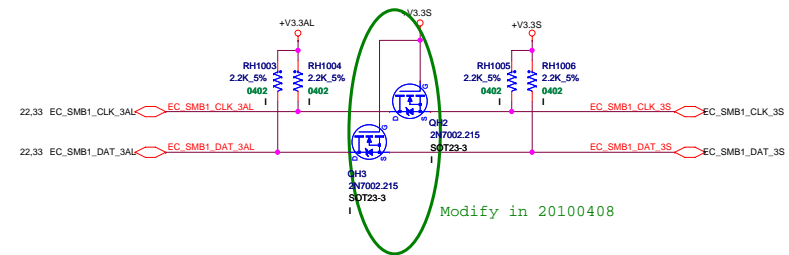
FAN CONNECTOR



AC Plug LED

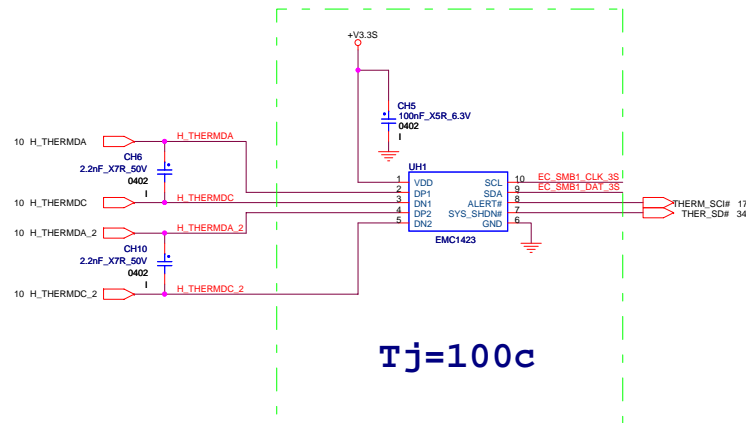


THERMAL SENSOR

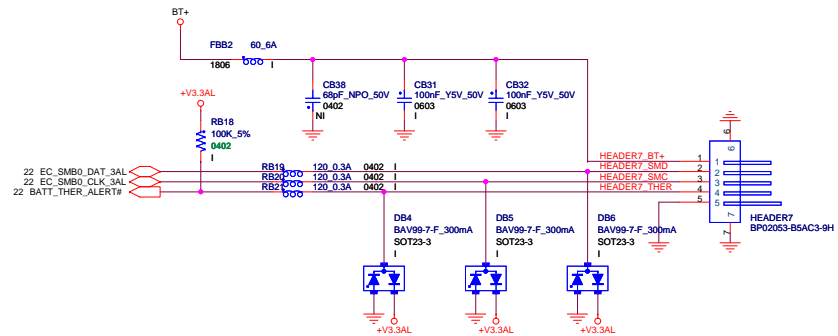
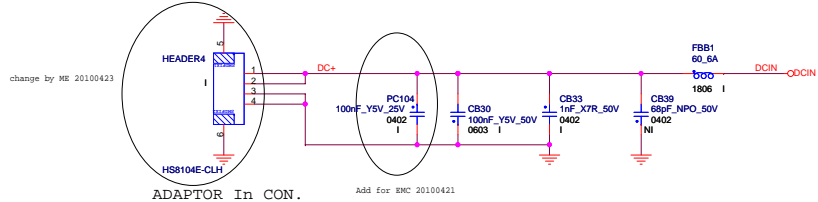


/ Modify in 20100408

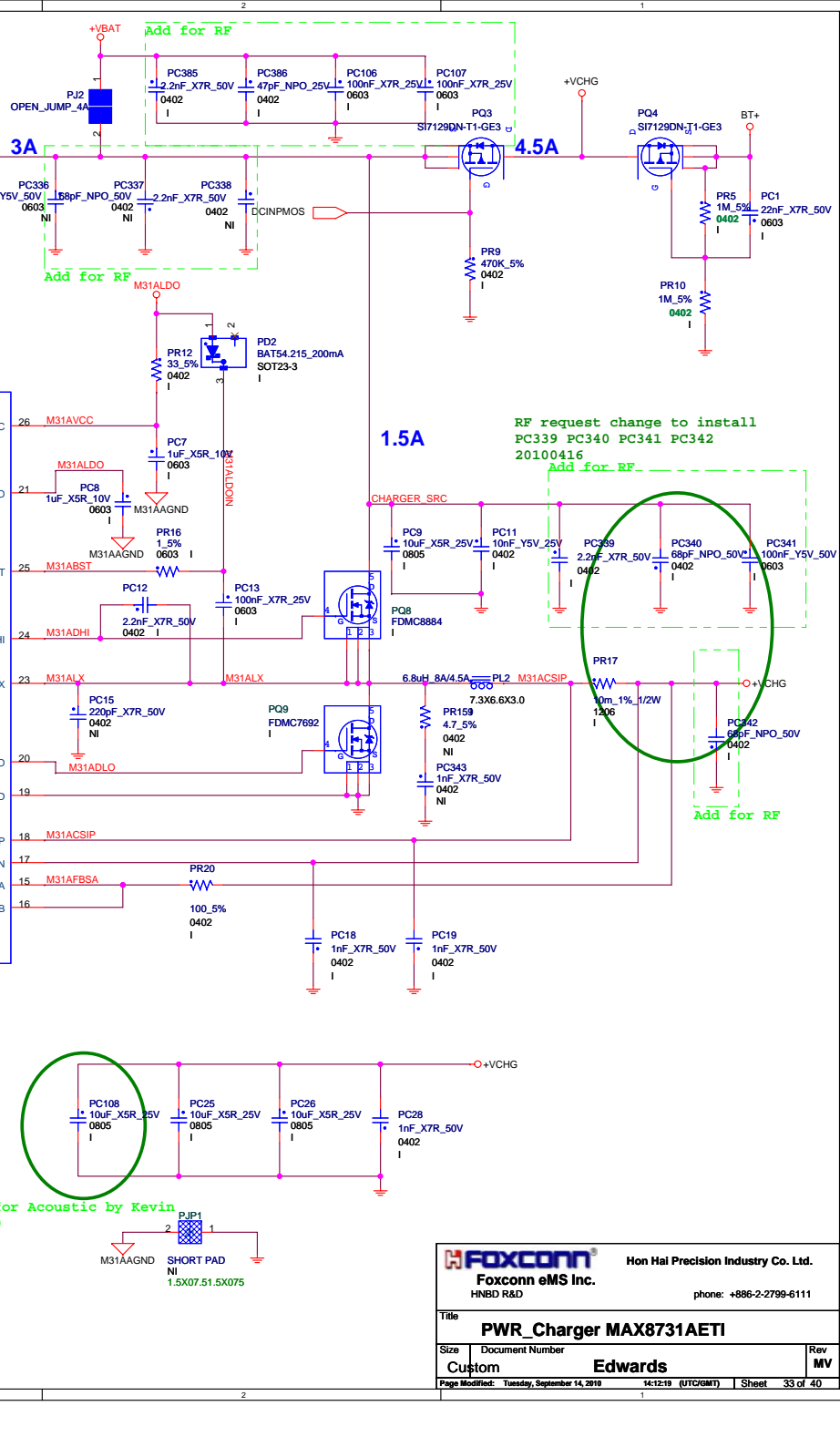
Add for Dual Core use


$$T_j = 100c$$

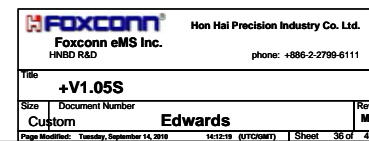
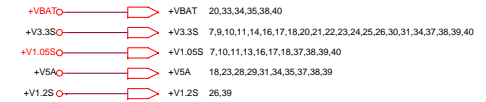
DC_JACK Wire to Board Connector



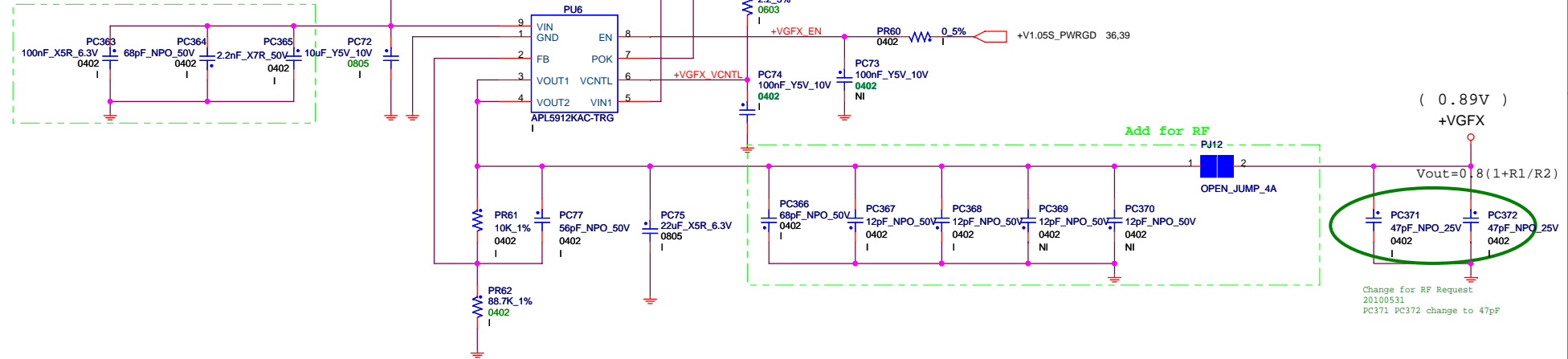
BATTERY CONNECTOR



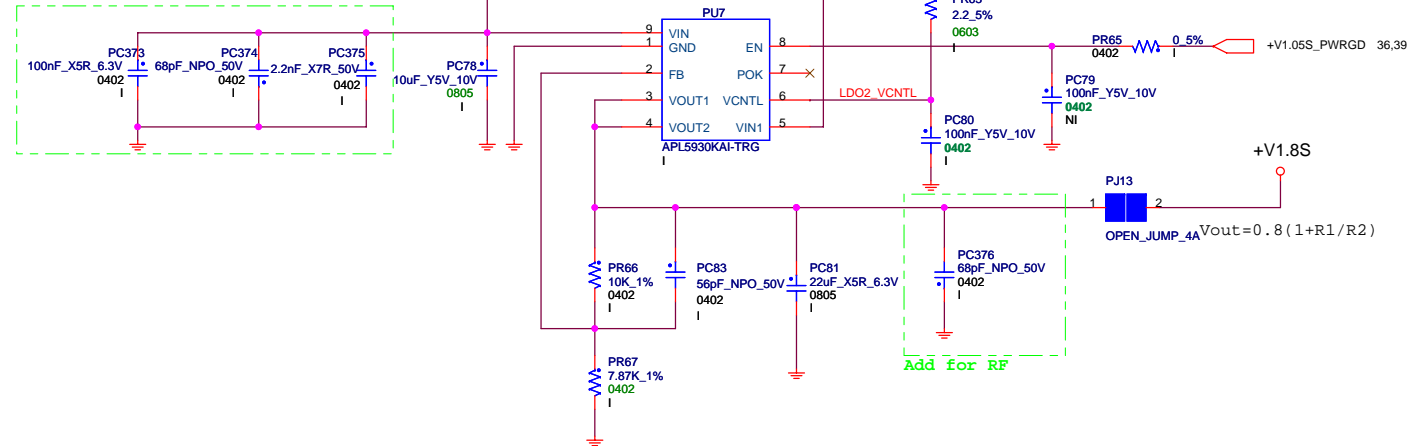


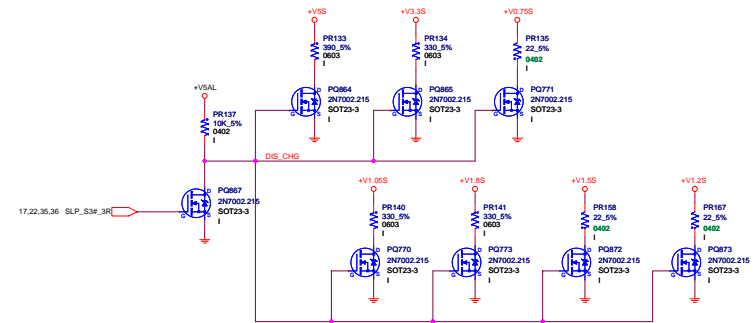


Add for RF



Add for RF





+V3.3Q		+V3.3S	7,8,10,11,14,16,17,18,20,21,22,23,24,25,26,30,31,34,36,37,38,39
+V3.3A		+V3.3A	15,17,18,21,22,24,33,34,35,39
+VSS		+VSS	16,18,20,23,28,30,31,36,38,39
+V5A		+V5A	18,23,28,29,31,34,35,36,37,38,39
+VBATO		+VBAT	20,33,34,35,36,38
+V1.05S		+V1.05S	7,10,11,13,16,17,18,36,37,38,39

For EMI Decoupling and All 47pF Caps are all RF Request

For RF Decoupling

All 47pF are RF Request in SI-Small build phase

